



### 60V +175°C DUAL N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

# **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
60V	$25m\Omega @ V_{GS} = 10V$	32A
60 V	$40 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$	25A

# **Description**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance making it ideal for high efficiency power management applications.

# **Applications**

- Backlighting
- Power-Management Functions
- DC-DC Converters

### **Features and Benefits**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- High-Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On-State Losses
- Low-Input Capacitance
- Fast-Switching Speed
- Wettable Flank for Improved Optical Inspections
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMNH6021SPDWQ)

### **Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed Over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Weight: 0.097 grams (Approximate)



Top View



**Bottom View** 

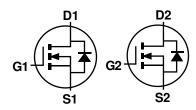
S1 [ ] D1

G1 [ ] D1

S2 [ ] D2

Pin 1 G2 [ ] D2

Pin Out
Top View



Equivalent Circuit

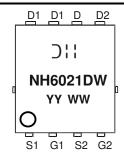
### **Ordering Information** (Note 4)

Part Number		Case	Packaging	
	DMNH6021SPDW-13	PowerDI5060-8 (SWP) (Type R)	2500 / Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



Oll = Manufacturer's Marking
NH6021DW = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 19 = 2019)
WW = Week (01 to 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	60	V	
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 6) $V_{GS} = 10V$ $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		I <sub>D</sub>	8.2 6.5	А
Continuous Drain Current (Note 7) $V_{GS} = 10V$ $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$		I <sub>D</sub>	32 22	А
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	80	Α	
Maximum Continuous Body Diode Forward Current (Note 7)	Is	32	Α	
Avalanche Current, L = 0.1mH (Note 8)	I <sub>AS</sub>	35	Α	
Avalanche Energy, L = 0.1mH (Note 8)	E <sub>AS</sub>	64	mJ	

# Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

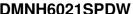
Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)	$P_{D}$	1.5	W		
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ hetaJA}$	99	°C/W	
Thermal Nesistance, bunction to Ambient (Note 3)	t<10s		53		
Total Power Dissipation (Note 6)	$P_{D}$	2.8	W		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	П	54	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{ hetaJA}$	27	G/VV	
Thermal Resistance, Junction to Case (Note 7)	$R_{ heta JC}$	2.2	°C/W		
Operating and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 to +175	°C		

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

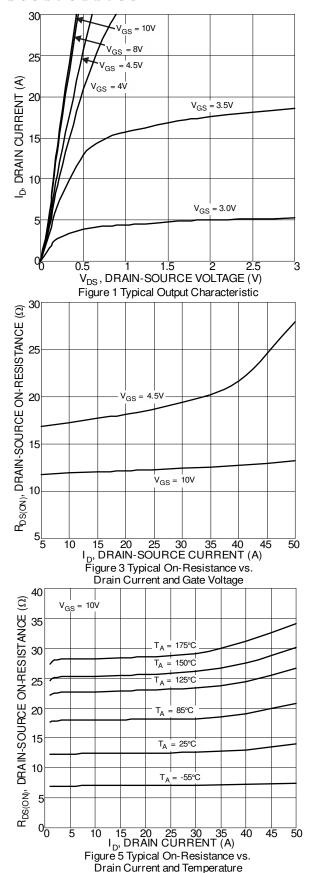
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 60V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)						•	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	3	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance		_	15	25	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 15A	
Static Diam-Source On-nesistance	R <sub>DS(ON)</sub>	_	21	40	11122	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 12A	
Diode Forward Voltage	$V_{SD}$	-	0.75	1.2	V	$V_{GS} = 0V, I_S = 2.6A$	
DYNAMIC CHARACTERISTICS (Note 10)				•			
Input Capacitance	Ciss	_	1,143	_	pF	V 05V V 0V	
Output Capacitance	Coss	_	168	_	pF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		69	_	pF	T = TIMEZ	
Gate Resistance	$R_g$	_	2.5	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	20.1	_	nC		
Total Gate Charge (V <sub>GS</sub> = 6V)		_	12	_	nC	7, , , , , , , , , , , , , , , , , , ,	
Gate-Source Charge	Q <sub>gs</sub>	_	4.3	_	nC	$V_{DS} = 30V, I_D = 20A$	
Gate-Drain Charge	$Q_{gd}$	_	5.5	_	nC	1	
Turn-On Delay Time	t <sub>D(ON)</sub>	-	4.4	_	ns		
Turn-On Rise Time	t <sub>R</sub>	-	6.0	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	14.2	_	ns	$R_g = 4.7\Omega, I_D = 20A$	
Turn-Off Fall Time	t <sub>F</sub>	_	5.4	_	ns	1 -	
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	21.2	_	ns		
Body Diode Reverse Recovery Charge		_	15.2	_	nC	$I_F = 20A$ , di/dt = 100A/ $\mu$ s	

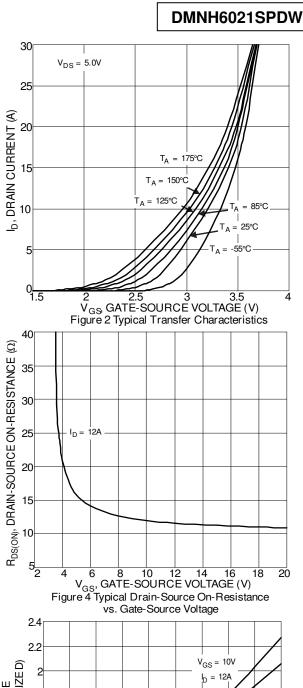
Notes:

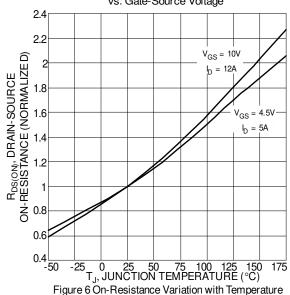
- 5. Device mounted on FR-4 PC board with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
  7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J$  = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.







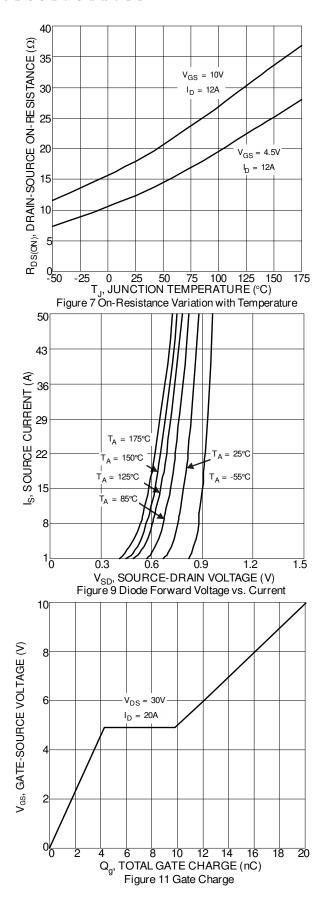


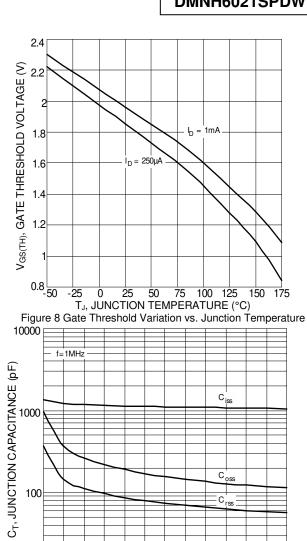


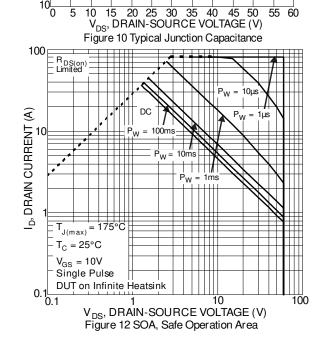
Coss

Crss

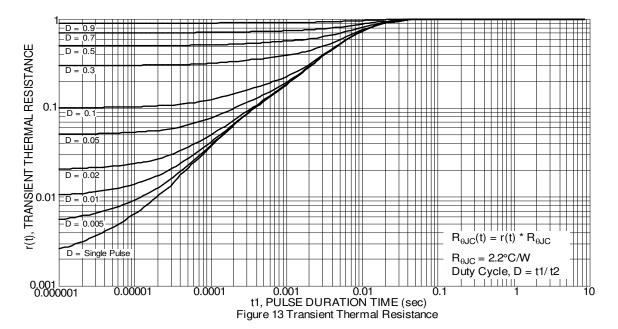










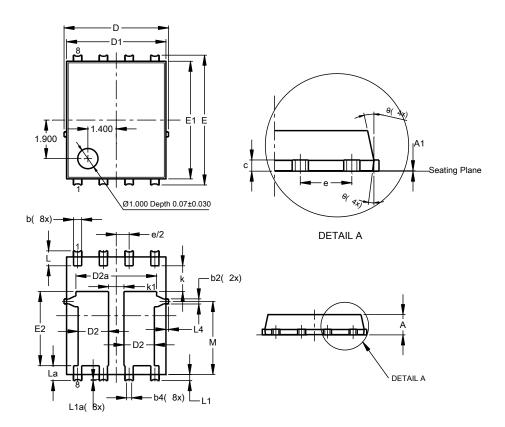




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI5060-8 (SWP) (Type R)

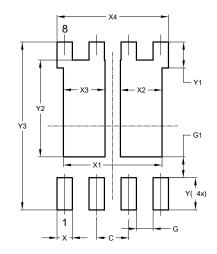


PowerDI5060-8 (SWP)					
(Type R)					
Dim	Min Max		Тур		
Α	0.90	1.10	1.00		
<b>A</b> 1	0	0.05			
b	0.30	0.50	0.41		
b2	0.20	0.35	0.25		
b4	(	).25REF	=		
С	0.230	0.330	0.277		
D	5	.15 BS0	)		
D1	4.70	5.10	4.90		
D2	1.40 1.60		1.50		
D2a	3.78 4.18		3.98		
Е	6	.40 BS0	)		
E1	5.60	6.00	5.80		
E2	3.46	3.86	3.66		
е	1	.27BSC	)		
k	1.05				
k1	0.56				
L	0.635	0.835	0.735		
La	0.635	0.835	0.735		
L1	0.200	0.400	0.300		
L1a	0.050REF				
L4	0.025	0.225	0.125		
M	3.205	4.005	3.605		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI5060-8 (SWP) (Type R)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
X	0.610		
X1	3.910		
X2	1.650		
Х3	1.650		
X4	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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